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38D2 群

ROM 修正功能

1. 要点

本篇资料介绍如何使用 38D2 群单片机的 ROM 修正功能。

2. 说明

该应用说明适用于以下条件：

采用的 MCU：38D2 群（例如：M38D24G4HP）

振荡频率： 10MHz

存储容量： ROM 16KB，RAM 640 字节

3. 内容

3.1 实例说明

- 38D2 群是 QzROM 单片机，正常情况下，它只能被烧写一次。但在空白未写保护的 ROM 区域，它可再次被追加烧入修正用程序码。例如，如图 1 所示，可以把初始程序代码烧入写保护区域 1，把修正用程序码追加烧入从 F000H 地址开始的未写保护区域。
- 在此实例中，选用 ROM 区域的 ROM 修正用向量 1 进行功能介绍（在实际应用中，可以同时使能 ROM 修正用向量 1 和 ROM 修正用向量 2）。在初始主程序中，有一条 Port 1 输出的指令。我们通过 ROM 修正功能对此端口输出值进行修正。
- 在此实例中，源程序设计软件工具为 HEW（High-performance Embedded Workshop 4.0.3.1）；烧写程序代码的软件工具为 FDT（Flash Development Toolkit 3.05）；MCU 类型为 M38D24G4HP。

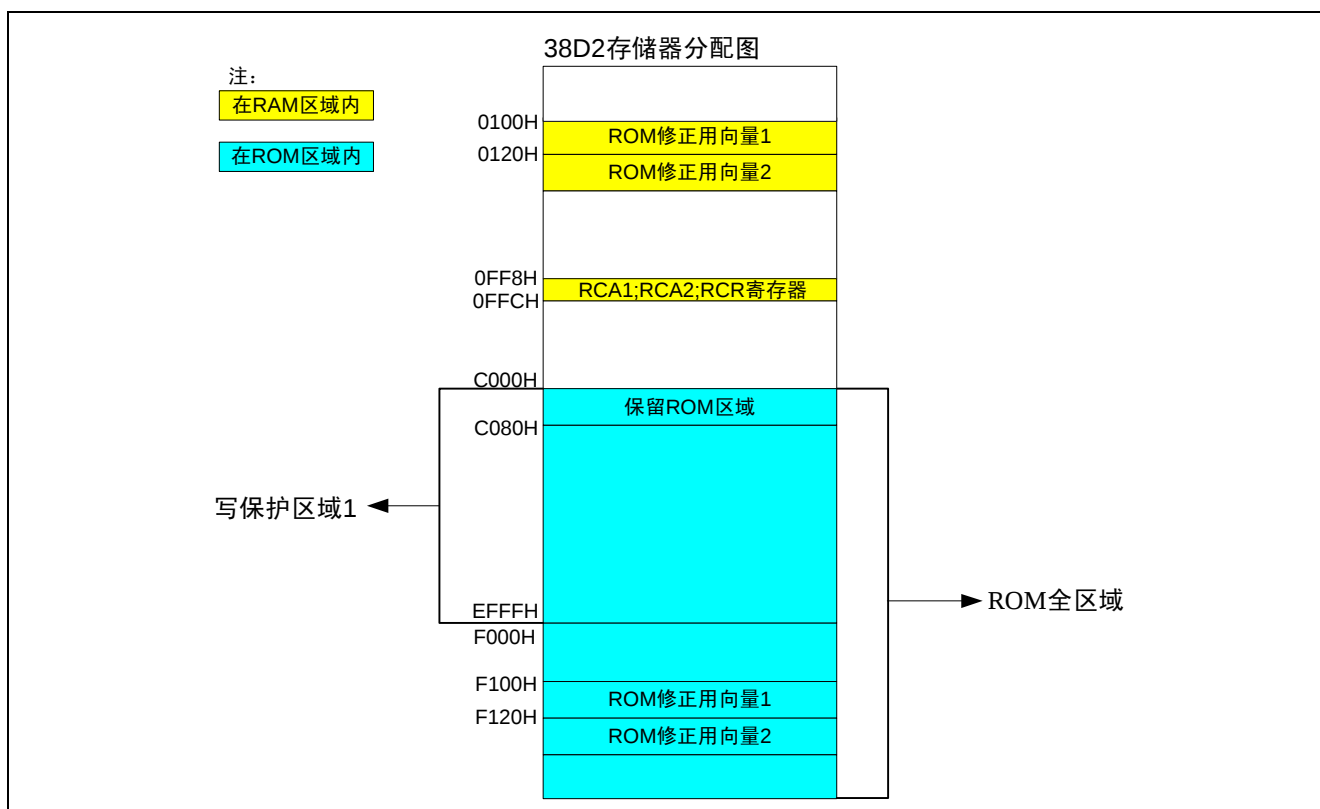


图 1. ROM 保护区域

3.2 操作

- 应用 FDT 烧写软件，从 C080H 开始首次烧入包含有可以使能 ROM 修正功能的初始程序代码。并设置对 ROM 区域 1 写保护。
- 安装此片 M38D2 单片机到用户系统板上，上电运行。可以观察到 P1 口的输出为 FFH。
- 从 F000H 开始（一个未写保护的空白 ROM 区域），追加烧入使能 ROM 修正功能的操作码。
- 从 ROM 修正用向量 1 的 F100H 开始，追加烧入修正用程序码。
- 再次安装此片 M38D2 单片机到用户系统板上，上电运行修正后的程序。可以观察到 P1 口输出为 0FH。

3.3 操作码设定

- 在初始程序中的错误指令
在初始程序中，有一条需要修正的错误指令，如图 2 所示。

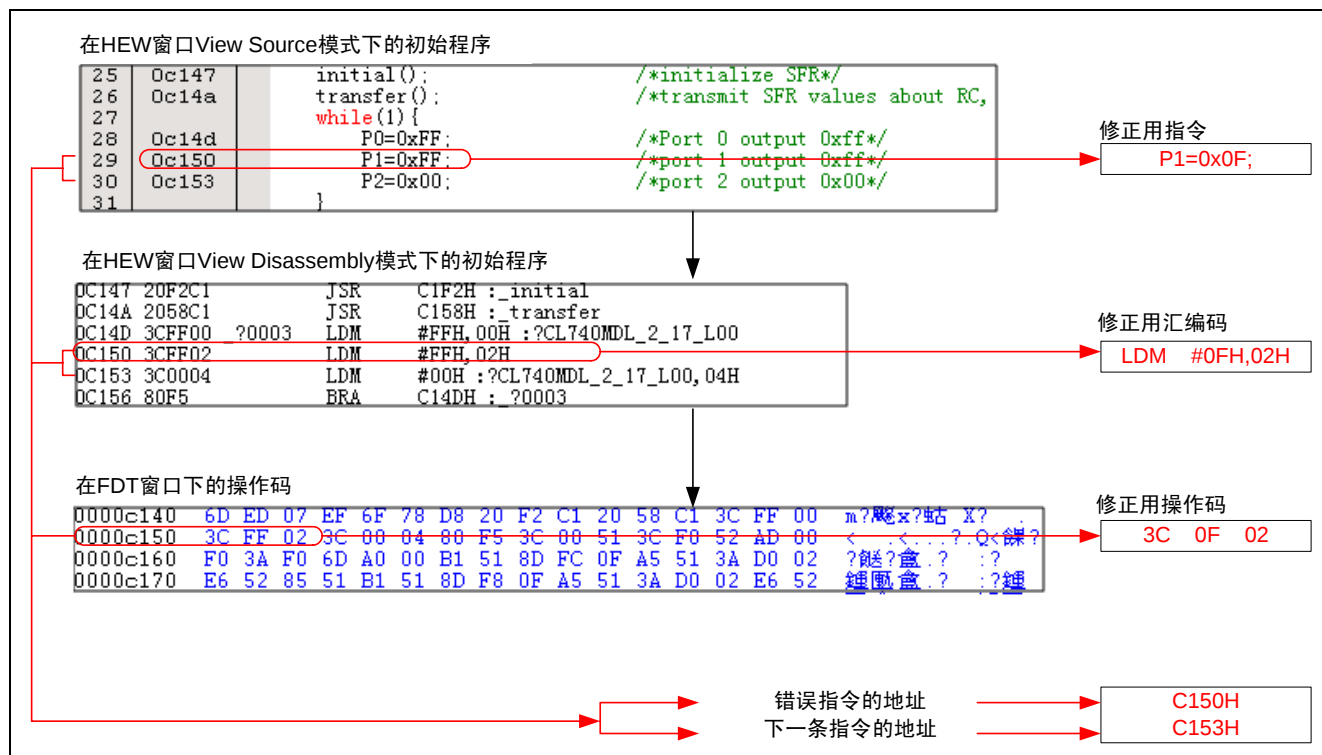


图 2. 初始程序中的错误指令

- ROM 修正功能相关的 SFR 设定
为使能 ROM 修正功能，需要从 F000H 开始的未写保护的空白 ROM 区域追加烧入 RCR、RCA1H 和 RCA1L 的设定值。此操作说明如图 3 所示。

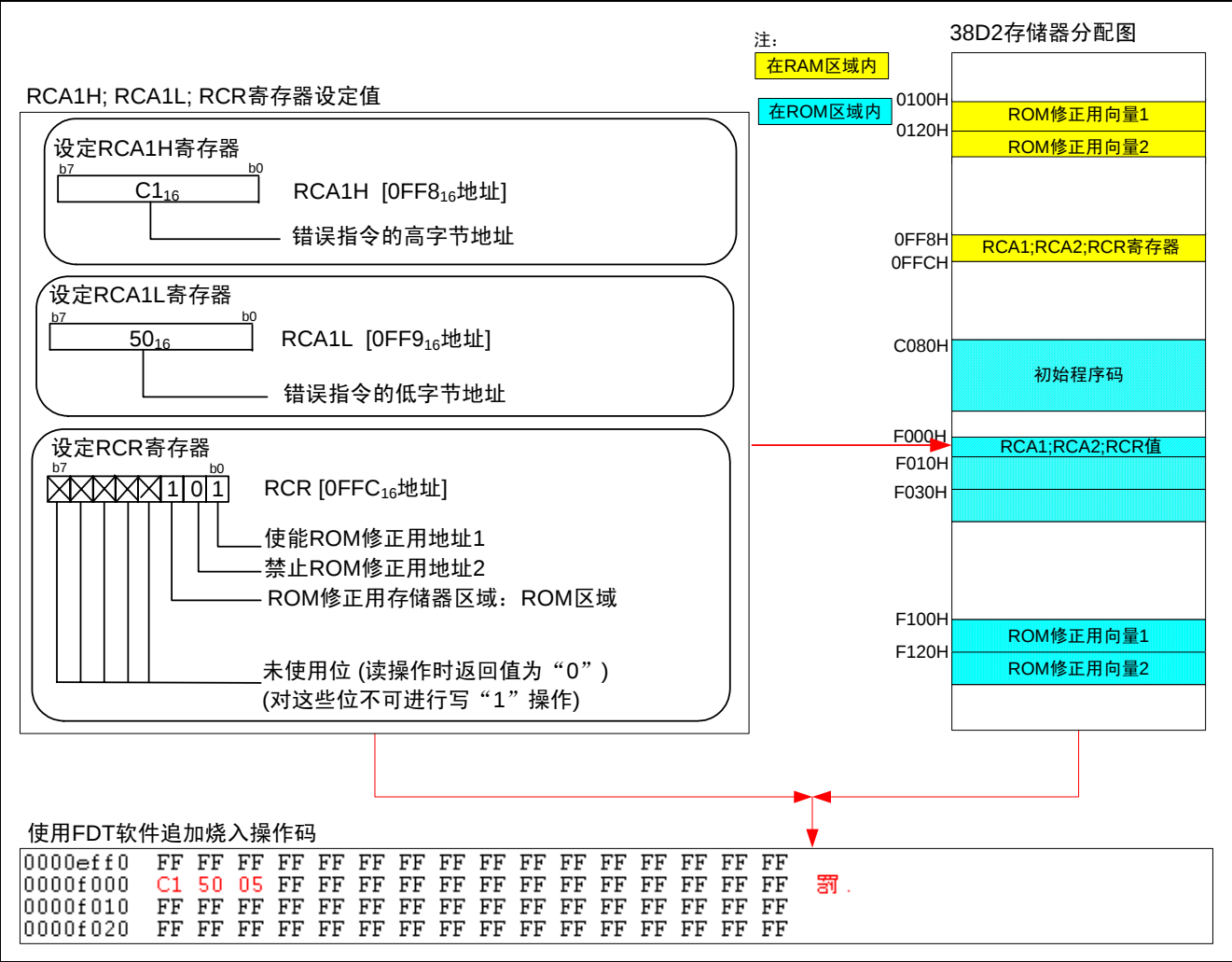


图 3. ROM 修正功能相关的 SFR 设定

- 修正用程序码
在此实例中，选用 ROM 区域的 ROM 修正用向量 1。所以把追加烧入的修正用程序码烧入此区域。应该注意，为使 PC（程序计数器）能从 ROM 修正用向量 1 返回，在追加的程序码后，需要加入一条 JMP 指令。此操作如图 4 所示。

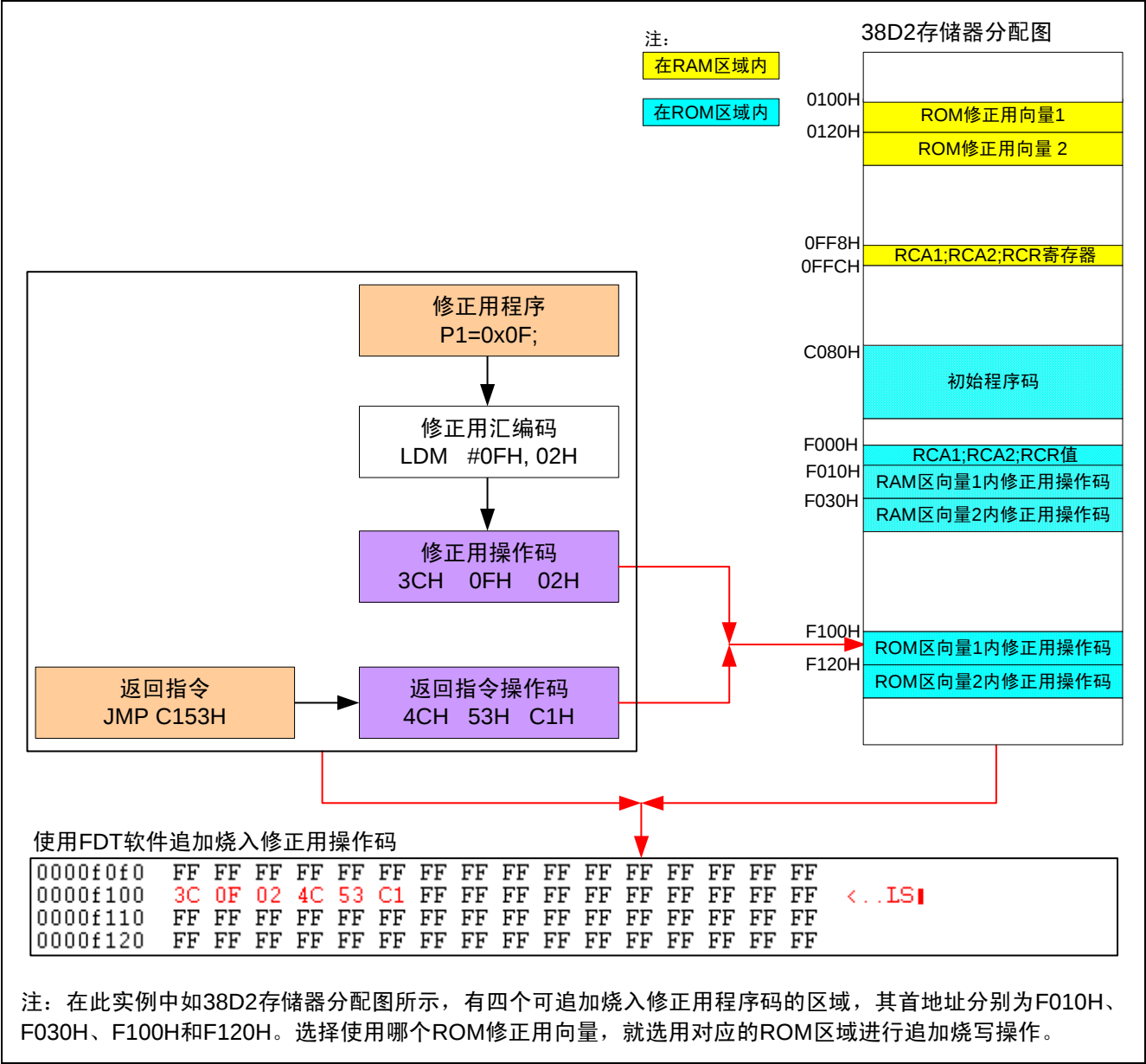


图 4. 修正用程序码

3.4 ROM 修正功能的实现

- 当程序被执行并且 PC（程序计数器）的值与在 ROM 修正地址寄存器里所设定的地址值相一致时，程序将自动跳转到 ROM 修正用向量并执行修正用程序。
- 在此实例中，当 PC（程序计数器）的值为 C150H 时，程序将自动跳转到 ROM 修正用向量 1（首地址为 F100H 的区域）去修正端口 1 的输出值。当执行到 JMP 指令时，程序将返回到初始程序的 C153H 地址处继续执行主程序。程序码的烧入操作如图 5 所示。实现 ROM 修正功能的原理如图 6 所示。

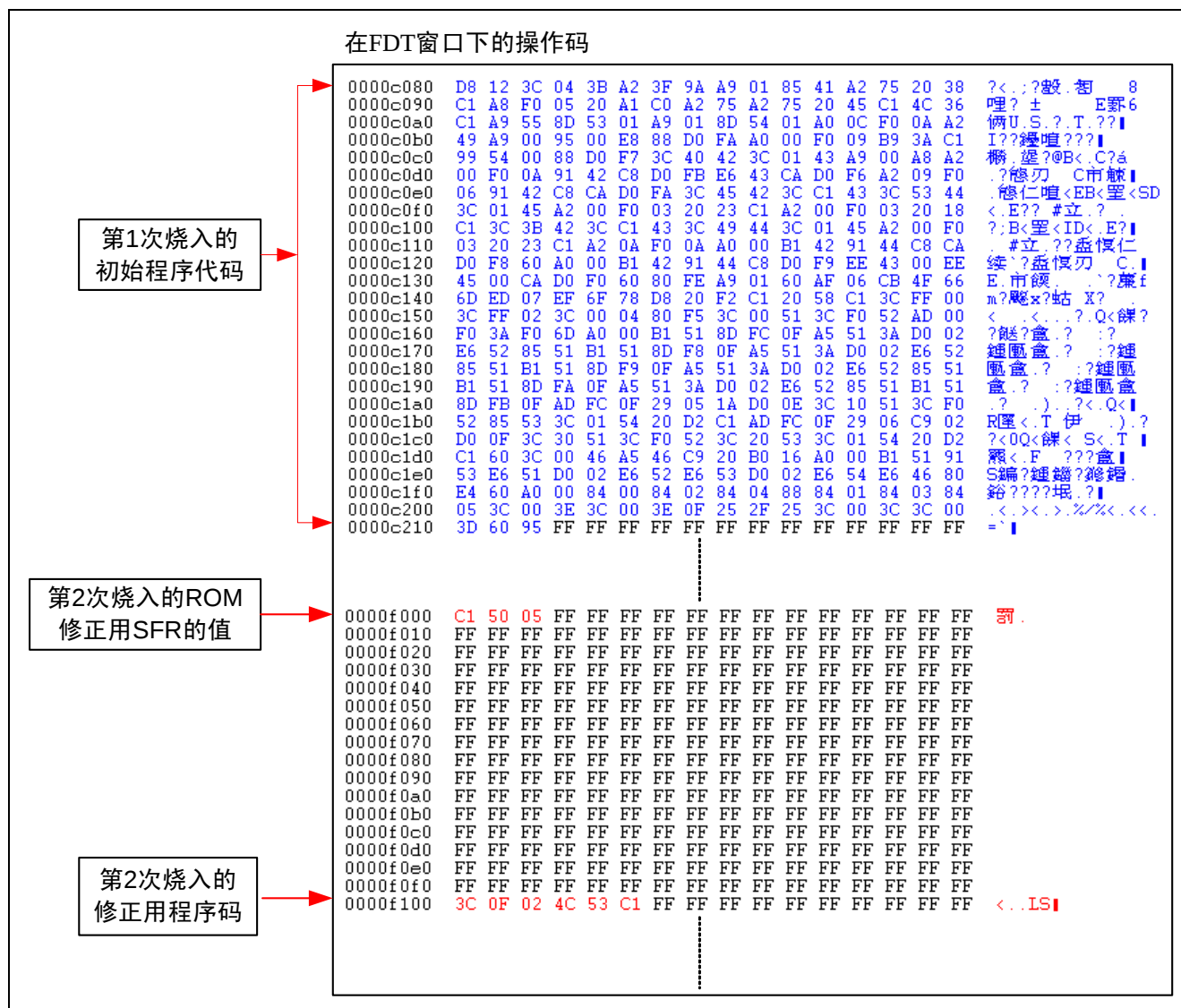


图 5. 程序码的烧入操作

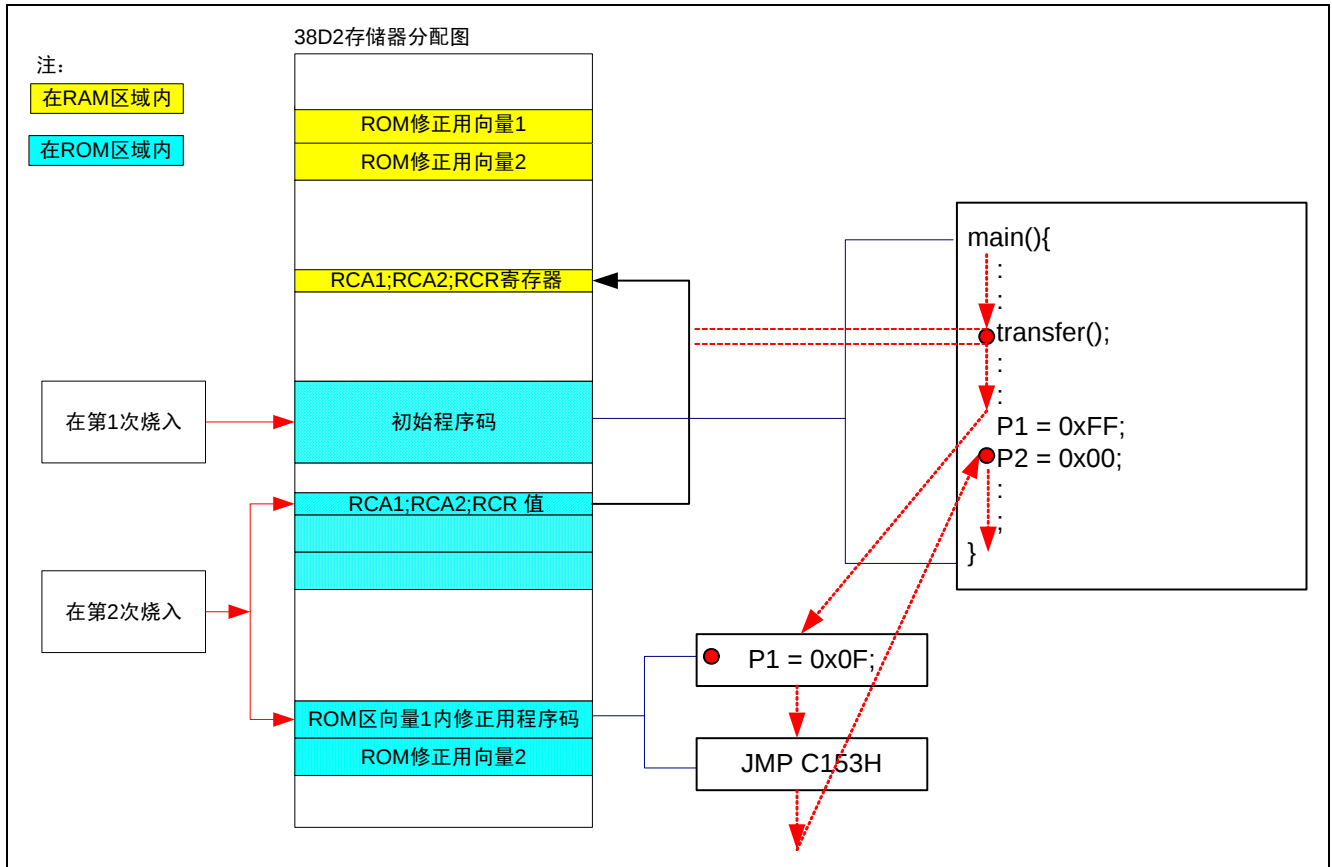
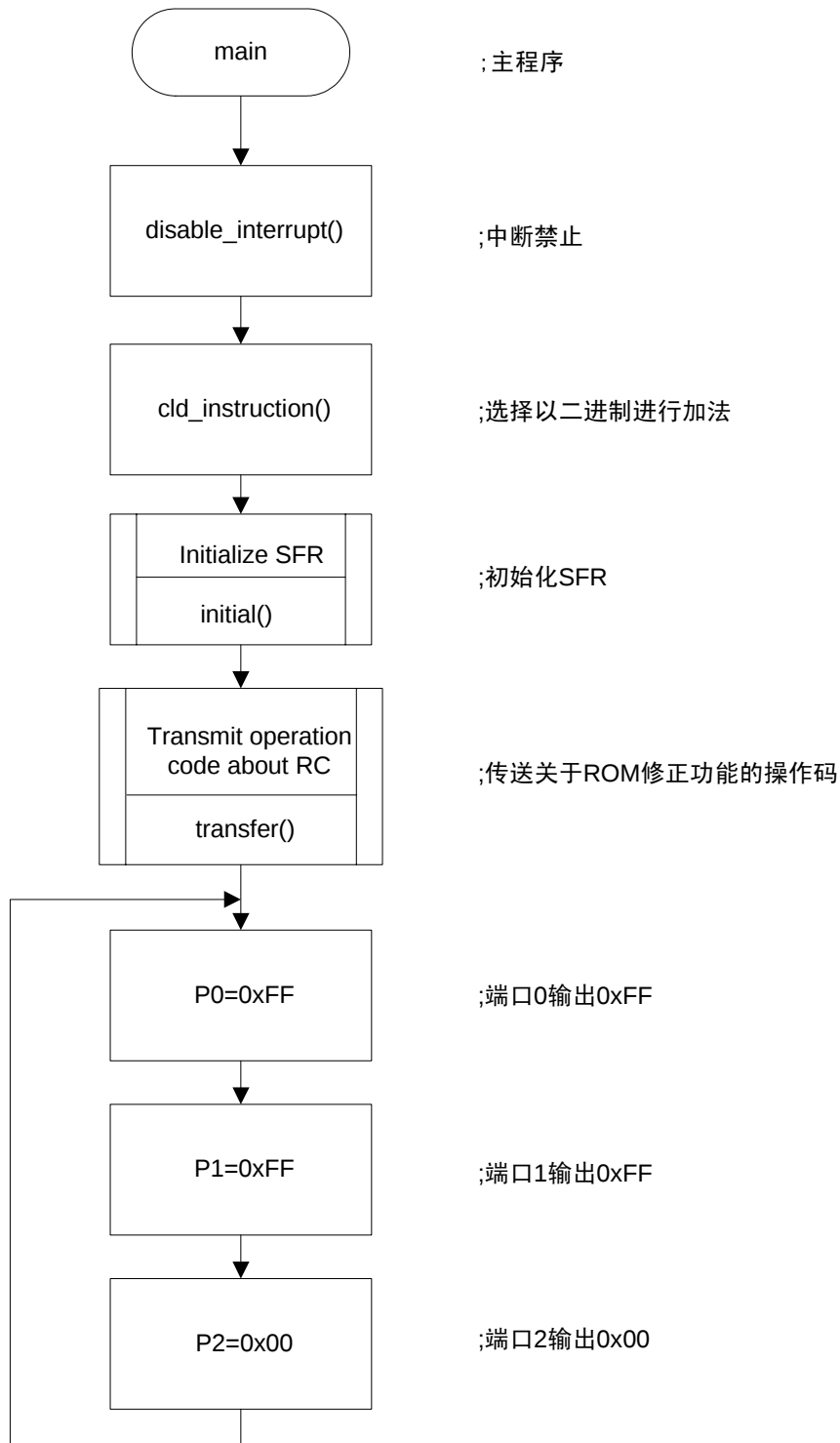


图 6. 实现 ROM 修正功能的过程

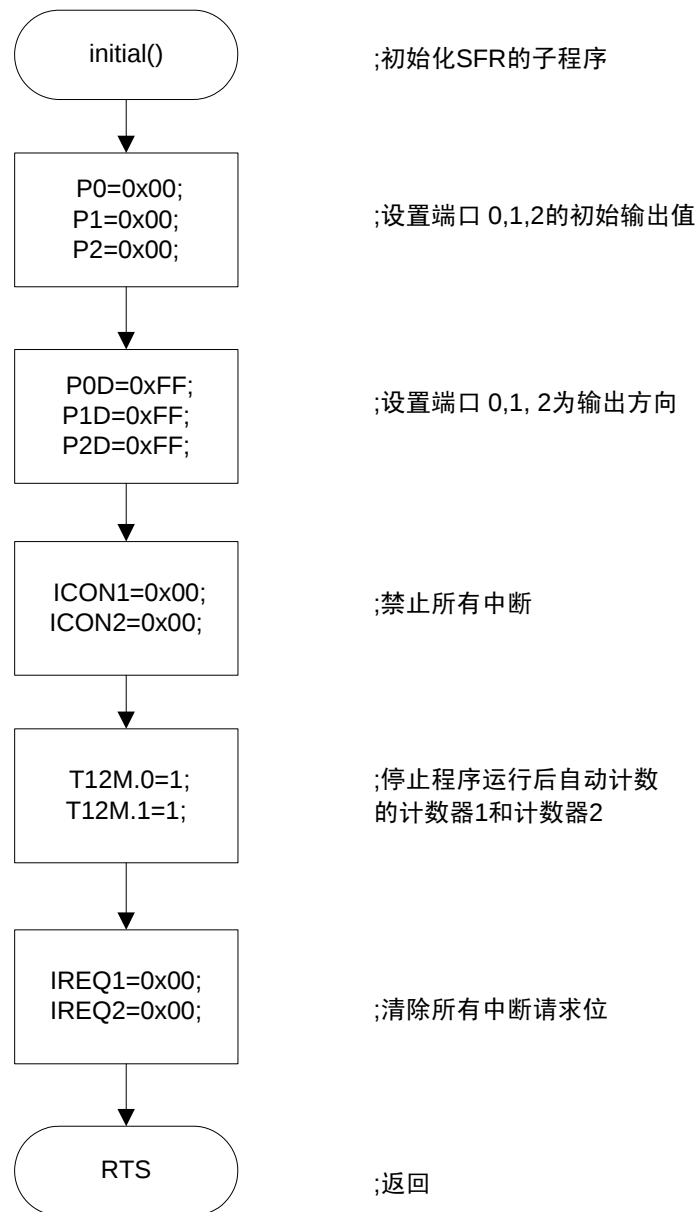
4. 流程图

下述内容为第一次烧入的初始程序的流程图。

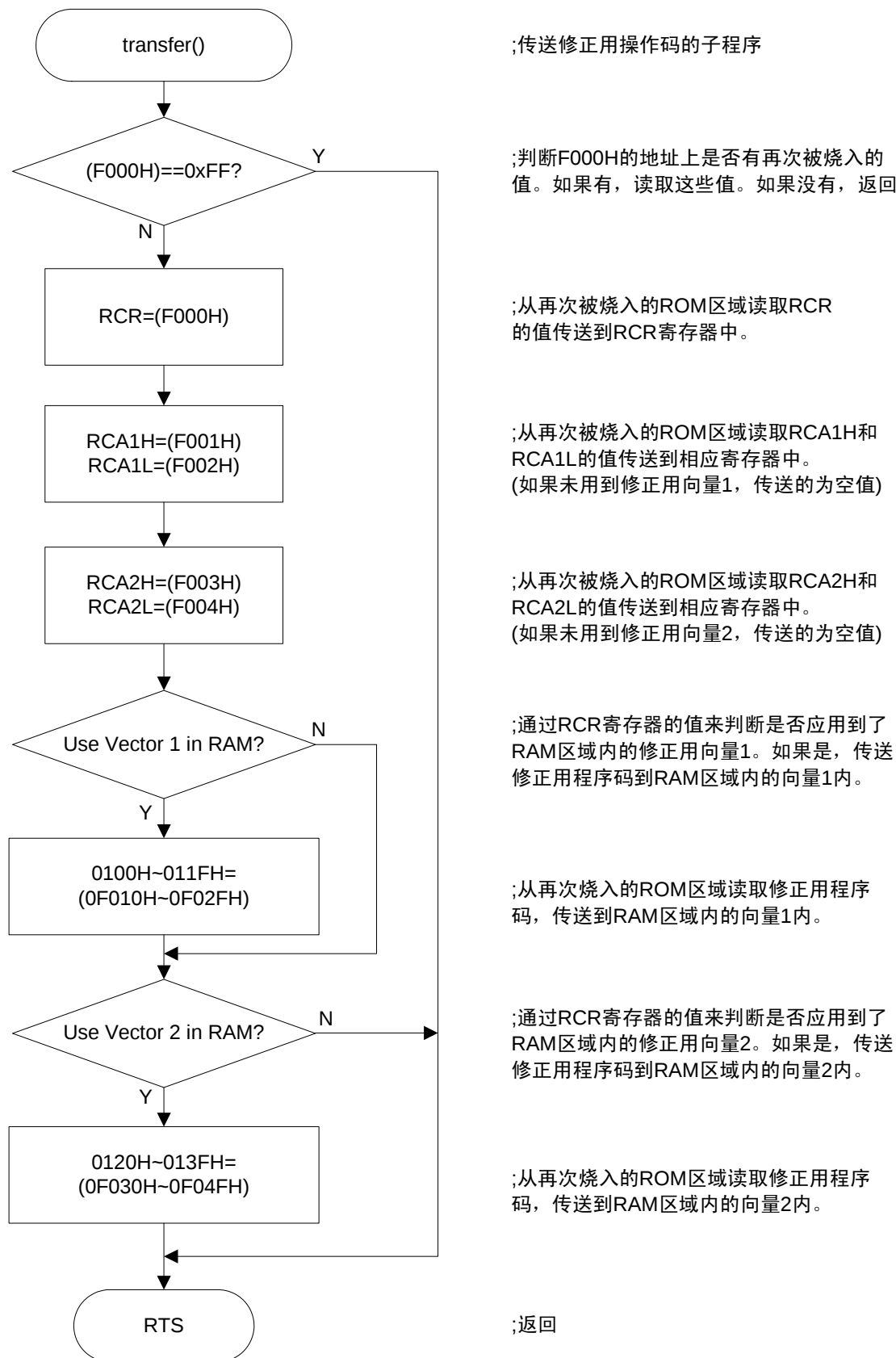
4.1 主程序流程图



4.2 子程序 initial 流程图



4.3 子程序 transfer 流程图



4.4 对于 transfer 子程序的说明

对应于上述 transfer 子程序的流程图，当使用 ROM 修正功能时，需要被再次烧入的操作码的位置和传送值的过程如图 7 所示。选择哪个修正用向量，就对应地设置相应的 RCR 寄存器的值，并且写入修正用程序码到对应的向量地址区域内。其他修正用向量地址区域内不需要设置任何值。

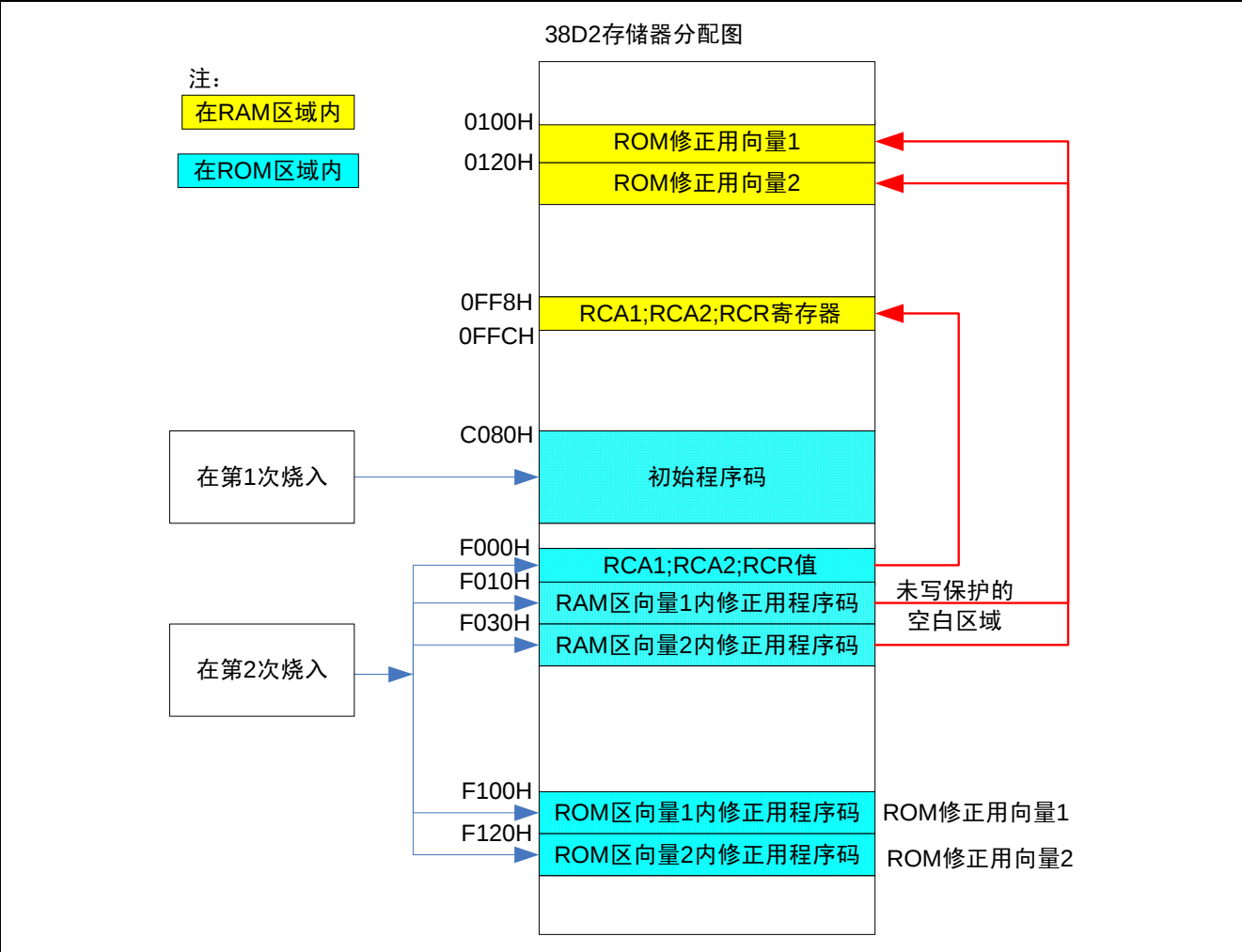


图 7. 对于 transfer 子程序的说明

5. 参考例程

下述内容为第一次烧入的初始程序的参考例程。

```

/*****
*   File Name      : rec05b0017_0100_source.c
*   CPU            : M38D24 Group
*   Function       : ROM Correction Function
*                   (use ROM correction vector 1)
*   Version        : 1.00 (2006-04-18)
*   Copyright (C) 2006, Renesas Technology Corp. All right reserved.
*****/

/*****
*   Include File
*****/
#include <intr740.h>
#include "io38d2.h"

/*****
*   Define Variable
*****/
zpage unsigned char *pt1_RC = 0x00;    /*address point in blank ROM area */
zpage unsigned char *pt2_RC = 0x00;    /*address point in SFR or RC vector*/

/*****
*   Function Declaration
*****/
void initial(void);                    /*initialize SFR subroutine*/
void transfer(void);                  /*transmit operation code subroutine*/
void transmit_pro_code(void);         /*transmit program code subroutine*/

/*****
Name      : Main
*****/
void main(void)
{
    disable_interrupt();              /* Interrupt Disable */
    cld_instruction();                /* Binary Arithmetic Executed */

    initial();                        /*initialize SFR*/
    transfer();                      /*transmit operation code subroutine*/
    while(1){
        P0 = 0xFF;                    /*Port 0 output 0xff*/
        P1 = 0xFF;                    /*port 1 output 0xff*/
        P2 = 0x00;                    /*port 2 output 0x00*/
    }
}

/*****
Name      : initial
Function   : initialize SFR
*****/
void initial(void){
    P0 = 0x00;                        /*port 0 output 0x00*/
    P1 = 0x00;                        /*port 1 output 0x00*/
    P2 = 0x00;                        /*port 2 output 0x00*/
    P0D = 0xFF;                      /*set port 0 to output direction*/
    P1D = 0xFF;                      /*set port 1 to output direction*/
}

```

```

P2D = 0xFF; /*set port 2 to output direction*/
ICON1 = 0x00; /*disable all interrupt*/
ICON1 = 0x00;
T12M.0 = 1; /*stop Timer 1*/
T12M.1 = 1; /*stop Timer 2*/
IREQ1 = 0x00; /*clear all interrupt request bits*/
IREQ2 = 0x00;
}
/*****
Name      : transfer
Function   : transmit operation code
*****/
void transfer(void){
    pt1_RC = (char *)0xF000; /*set the blank ROM area address*/

    if (*pt1_RC!=0xFF){ /*if there are values, transmit them*/

        RCR = *pt1_RC; /*set RCR register*/
        pt1_RC = pt1_RC+1;

        RCA1H = *pt1_RC; /*set RCA1H register*/
        pt1_RC = pt1_RC+1;
        RCA1L = *pt1_RC; /*set RCA1L register*/
        pt1_RC = pt1_RC+1;

        RCA2H = *pt1_RC; /*set RCA2H register*/
        pt1_RC = pt1_RC+1;
        RCA2L = *pt1_RC; /*set RCA2L register*/

        if ((RCR&0x05)==0x01){ /*if use RC vector 1 in RAM area*/
            pt1_RC = (char *)0xF010; /*set program code address in F010H*/
            pt2_RC = (char *)0x0100; /*point to RC vector 1 address*/
            transmit_pro_code(); /*transmit program code to RC vector 1*/
        }
        if ((RCR&0x06)==0x02){ /*if use RC vector 2 in RAM area*/
            pt1_RC = (char *)0xF030; /*set program code address in F030H*/
            pt2_RC = (char *)0x0120; /*point to RC vector 2 address*/
            transmit_pro_code(); /*transmit program code to RC vector 2*/
        }
    }
}
/*****
Name      : transmit_pro_code
Function   : transmit program code to RC vector in RAM if use them
*****/
void transmit_pro_code(void){
    zpage unsigned char k = 0x00;
    for(k=0;k<32;k++){ /*loop for transmitting program code*/
        *pt2_RC = *pt1_RC; /*execute transmitting*/
        pt1_RC++; /*blank ROM area address increase*/
        pt2_RC++; /*RC vector address increase*/
    }
}

```

6. 参考文献

硬件手册

38D2 群数据手册

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 - 4) 其他直接影响到人的生命的装置。
9. 在使用本资料所记载的产品时，对于最大额定值、工作电源电压的范围、放热特性、安装条件及其他条件请在本公司规定的保证范围内使用。如果超出了本公司规定的保证范围使用时，对于由此而造成的故障和出现的事故，本公司将不承担任何责任。
10. 本公司一直致力于提高产品的质量和可靠性，但一般来说，半导体产品总会以一定的概率发生故障、或者由于使用条件不同而出现错误运行等。为了避免因本公司的产品发生故障或者错误运行而导致人身事故和火灾或造成社会性的损失，希望客户能自行负责进行冗余设计、采取延烧对策及进行防止错误运行等的安全设计（包括硬件和软件两方面的设计）以及老化处理等，这是作为机器和系统的出厂保证。特别是单片机的软件，由于单独进行验证很困难，所以要求在顾客制造的最终的机器及系统上进行安全检验工作。
11. 如果把本资料所记载的产品从其载体设备上卸下，有可能造成婴儿误吞的危险。顾客在将本公司产品安装到顾客的设备上时，请顾客自行负责将本公司产品设置为不容易剥落的安全设计。如果从顾客的设备上剥落而造成事故时，本公司将不承担任何责任。
12. 在未得到本公司的事先书面认可时，不可将本资料的一部分或者全部转载或者复制。
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